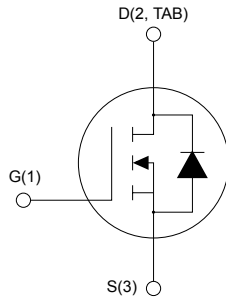
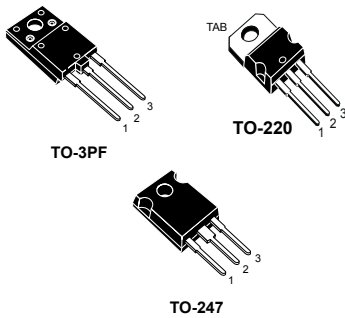


## N-channel 1500 V, 6 $\Omega$ typ., 4 A, PowerMESH Power MOSFET in TO-220, TO-247 and TO-3PF packages



AM01475v1\_noZen

### Features

- 100% avalanche tested
- Intrinsic capacitances and  $Q_g$  minimized
- High speed switching
- Fully isolated TO-3PF plastic package

### Applications

- Switching applications

### Description

These Power MOSFETs are designed using the STMicroelectronics consolidated strip-layout-based MESH OVERLAY process. The result is a product that matches or improves on the performance of comparable standard parts from other manufacturers.



#### Product status links

[STFW4N150](#)
[STP4N150](#)
[STW4N150](#)

# 1 Electrical ratings

**Table 1. Absolute maximum ratings**

Symbol	Parameter	Value			Unit
		TO-3PF	TO-220	TO-247	
V <sub>DS</sub>	Drain-source voltage	1500			V
V <sub>GS</sub>	Gate-source voltage	±30			V
I <sub>D</sub>	Drain current (continuous) at T <sub>C</sub> = 25 °C	4 <sup>(1)</sup>	4	4	A
	Drain current (continuous) at T <sub>C</sub> = 100 °C	2.5 <sup>(1)</sup>	2.5	2.5	
I <sub>DM</sub> <sup>(2)</sup>	Drain current (pulsed)	12	12	12	A
P <sub>TOT</sub>	Total power dissipation at T <sub>C</sub> = 25 °C	63	160		W
V <sub>ISO</sub>	Insulation withstand voltage (RMS) from all three leads to external heat sink (t = 1 s; T <sub>C</sub> = 25 °C)	3.5			kV
T <sub>stg</sub>	Storage temperature range	-55 to 150			°C
T <sub>J</sub>	Operating junction temperature range				

1. Limited by maximum junction temperature.
2. Pulse width limited by safe operating area.

**Table 2. Thermal data**

Symbol	Parameter	Value			Unit
		TO-3PF	TO-220	TO-247	
R <sub>thJC</sub>	Thermal resistance, junction-to-case	2	0.78		°C/W
R <sub>thJA</sub>	Thermal resistance, junction-to-ambient	50	62.5	50	°C/W

**Table 3. Avalanche characteristics**

Symbol	Parameter	Value	Unit
I <sub>AR</sub>	Avalanche current, repetitive or not-repetitive (pulse width limited by T <sub>J</sub> max)	4	A
E <sub>AS</sub>	Single pulse avalanche energy (starting T <sub>J</sub> = 25 °C, I <sub>D</sub> = I <sub>AR</sub> , V <sub>DD</sub> = 50 V)	350	mJ

## 2 Electrical characteristics

( $T_C = 25\text{ °C}$  unless otherwise specified)

**Table 4. Static**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$V_{(BR)DSS}$	Drain-source breakdown voltage	$V_{GS} = 0\text{ V}$ , $I_D = 1\text{ mA}$	1500			V
$I_{DSS}$	Zero gate voltage drain current	$V_{GS} = 0\text{ V}$ , $V_{DS} = 1500\text{ V}$			10	$\mu\text{A}$
		$V_{GS} = 0\text{ V}$ , $V_{DS} = 1500\text{ V}$ , $T_C = 125\text{ °C}$ <sup>(1)</sup>			500	
$I_{GSS}$	Gate-body leakage current	$V_{DS} = 0\text{ V}$ , $V_{GS} = \pm 30\text{ V}$			$\pm 100$	nA
$V_{GS(th)}$	Gate threshold voltage	$V_{DS} = V_{GS}$ , $I_D = 250\text{ }\mu\text{A}$	3	4	5	V
$R_{DS(on)}$	Static drain-source on-resistance	$V_{GS} = 10\text{ V}$ , $I_D = 2\text{ A}$		6	7	$\Omega$

1. Specified by design, not tested in production.

**Table 5. Dynamic**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$C_{iss}$	Input capacitance	$V_{DS} = 25\text{ V}$ , $f = 1\text{ MHz}$ , $V_{GS} = 0\text{ V}$	-	1100		pF
$C_{oss}$	Output capacitance		-	120		pF
$C_{rSS}$	Reverse transfer capacitance		-	12		pF
$Q_g$	Total gate charge	$V_{DD} = 600\text{ V}$ , $I_D = 4\text{ A}$ , $V_{GS} = 0\text{ to }10\text{ V}$ (see Figure 18. Test circuit for gate charge behavior)	-	29	50 <sup>(1)</sup>	nC
$Q_{gs}$	Gate-source charge		-	8		nC
$Q_{gd}$	Gate-drain charge		-	12		nC

1. Specified by design, not tested in production.

**Table 6. Switching times**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$t_{d(on)}$	Turn-on delay time	$V_{DD} = 750\text{ V}$ , $I_D = 2\text{ A}$ , $R_G = 4.7\text{ }\Omega$ , $V_{GS} = 10\text{ V}$	-	34	-	ns
$t_r$	Rise time		-	31	-	ns
$t_{d(off)}$	Turn-off delay time	(see Figure 17. Test circuit for resistive load switching times and Figure 22. Switching time waveform)	-	47	-	ns
$t_f$	Fall time		-	45	-	ns

**Table 7. Source-drain diode**

Symbol	Parameter	Test conditions	Min.	Typ.	Max.	Unit
$I_{SD}$	Source-drain current		-		4	A
$I_{SDM}^{(1)}$	Source-drain current (pulsed)		-		12	A
$V_{SD}^{(2)}$	Forward on voltage	$V_{GS} = 0\text{ V}$ , $I_{SD} = 4\text{ A}$	-		2	V
$t_{rr}$	Reverse recovery time	$I_{SD} = 4\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	520		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 45\text{ V}$	-	3.1		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 19. Test circuit for inductive load switching and diode recovery times)	-	12		A
$t_{rr}$	Reverse recovery time	$I_{SD} = 4\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ ,	-	650		ns
$Q_{rr}$	Reverse recovery charge	$V_{DD} = 45\text{ V}$ , $T_J = 150\text{ }^\circ\text{C}$	-	4.1		$\mu\text{C}$
$I_{RRM}$	Reverse recovery current	(see Figure 19. Test circuit for inductive load switching and diode recovery times)	-	12.6		A

1. Pulse width is limited by safe operating area.
2. Pulse test: pulse duration = 300  $\mu\text{s}$ , duty cycle 1.5%.

## 2.1 Electrical characteristics (curves)

Figure 1. Safe operating area for TO-3PF

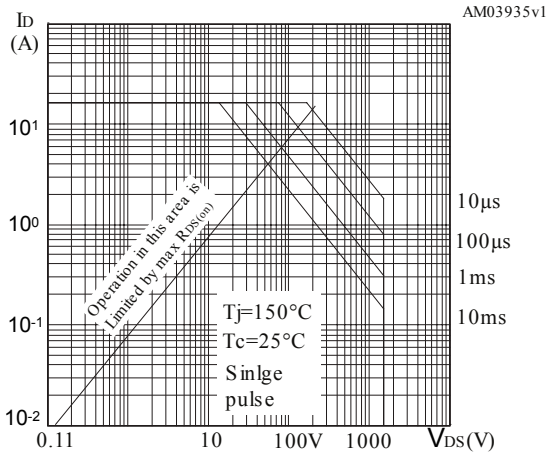


Figure 2. Normalized transient thermal impedance for TO-3PF

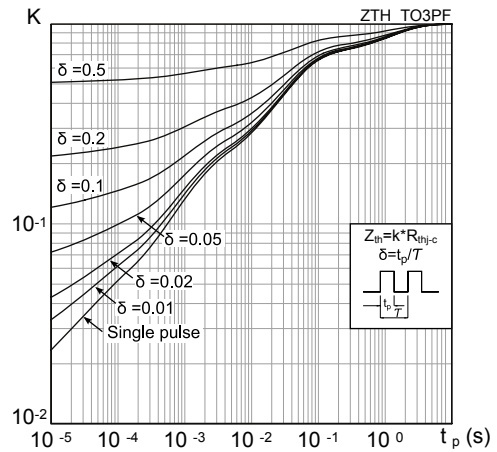


Figure 3. Safe operating area for TO-220

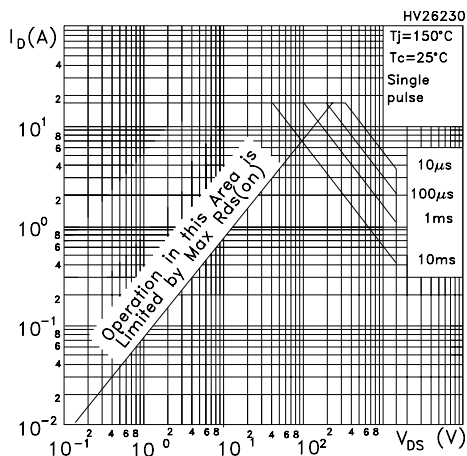


Figure 4. Normalized transient thermal impedance for TO-220

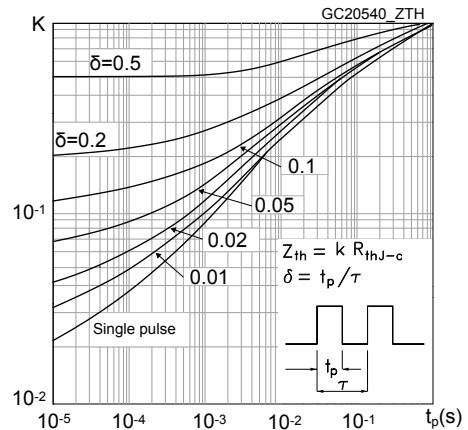


Figure 5. Safe operating area for TO-247

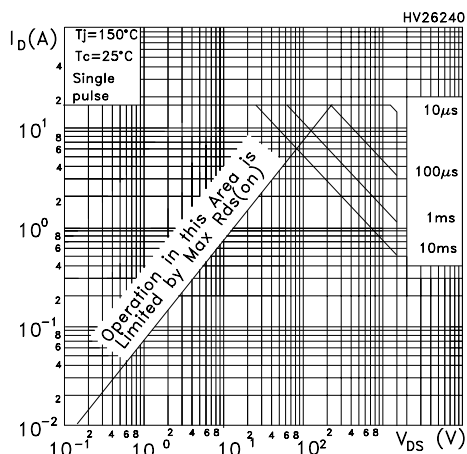


Figure 6. Normalized transient thermal impedance for TO-247

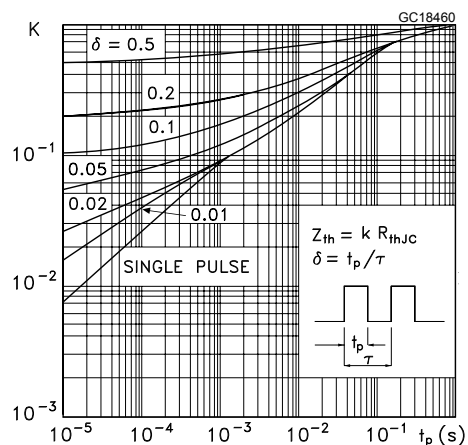


Figure 7. Typical output characteristics

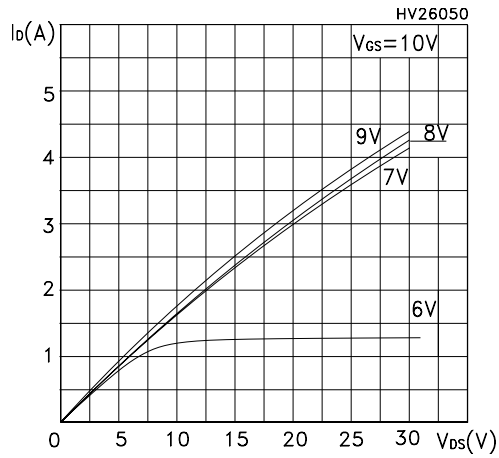


Figure 8. Typical transfer characteristics

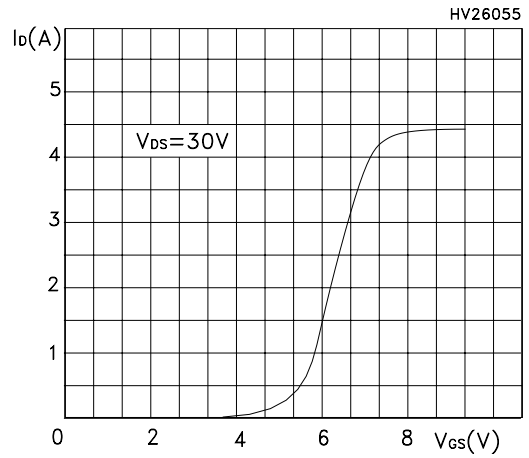


Figure 9. Normalized on-resistance vs temperature

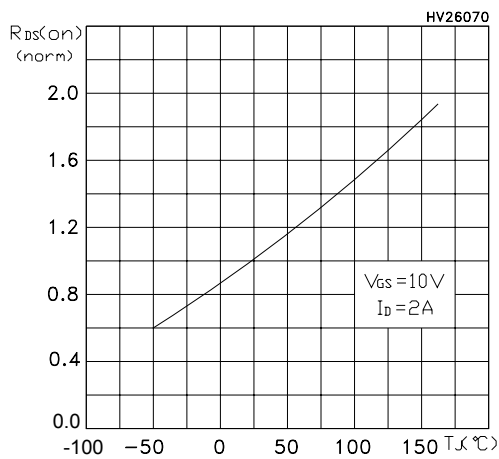


Figure 10. Typical drain-source on-resistance

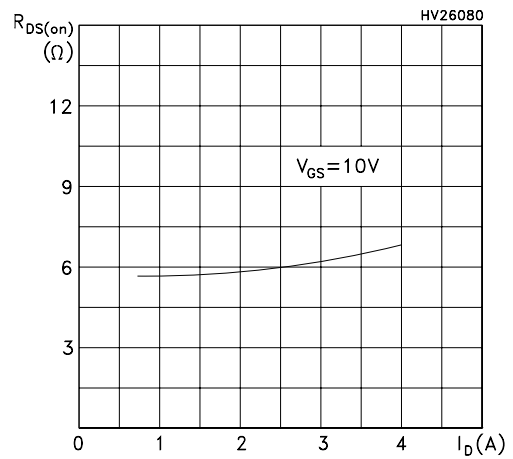


Figure 11. Typical gate charge characteristics

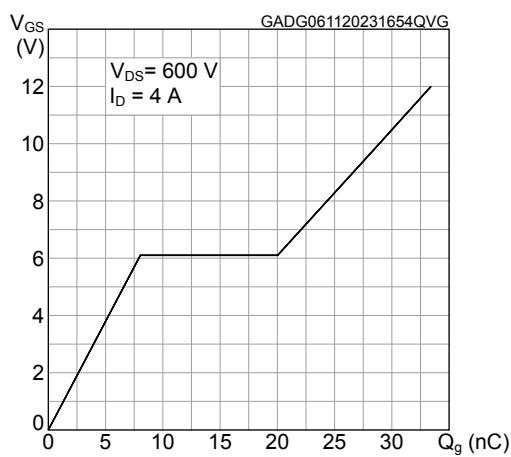


Figure 12. Typical capacitance characteristics

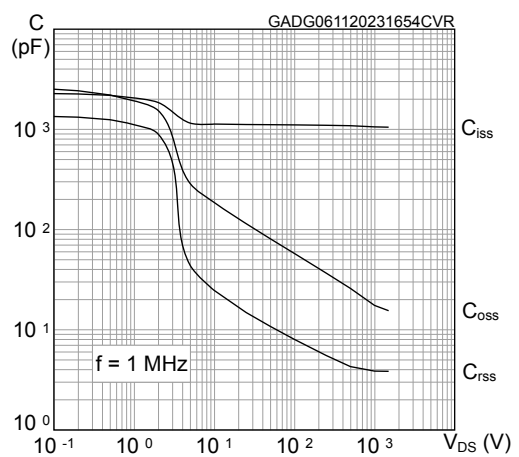


Figure 13. Normalized gate threshold vs temperature

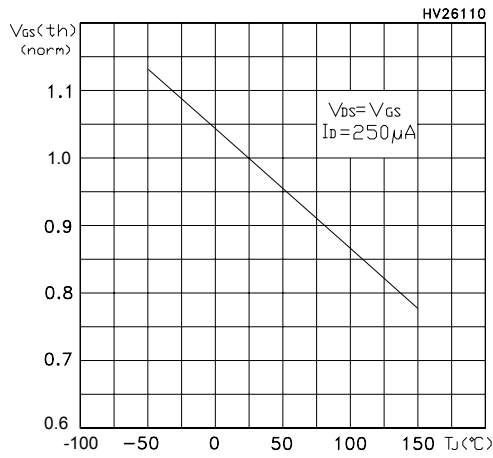


Figure 14. Normalized breakdown voltage vs temperature

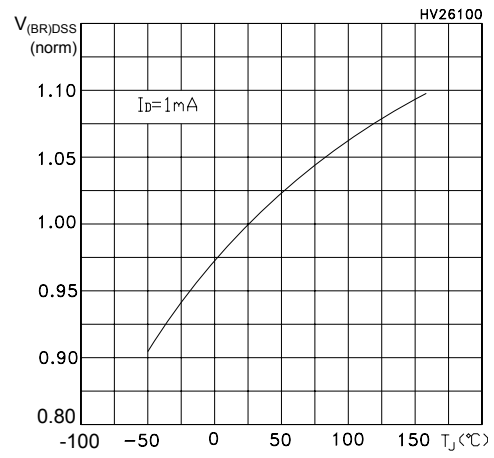


Figure 15. Typical reverse diode forward characteristics

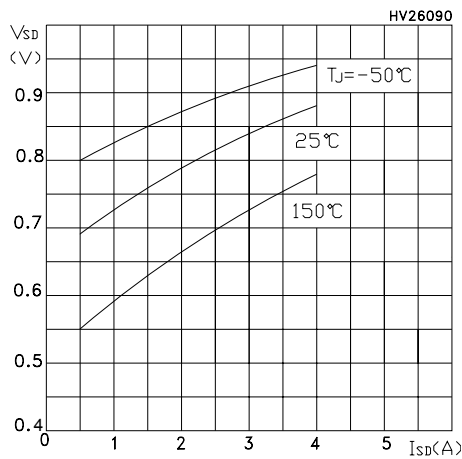
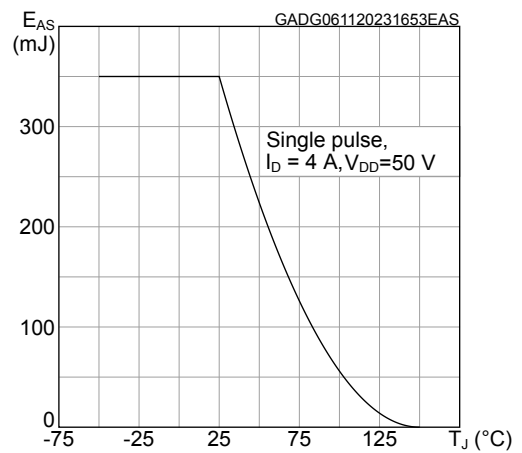
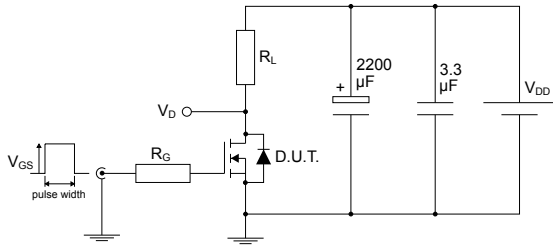


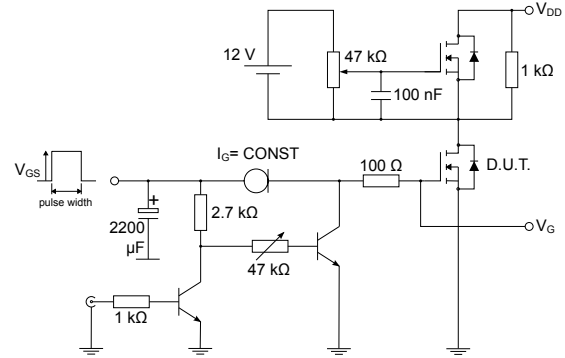
Figure 16. Maximum avalanche energy vs temperature



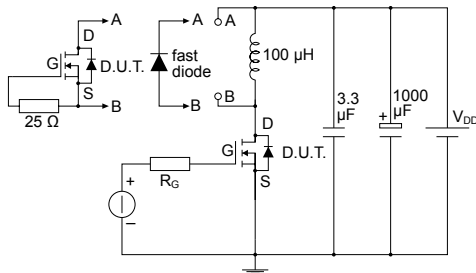
### 3 Test circuits

**Figure 17. Test circuit for resistive load switching times**


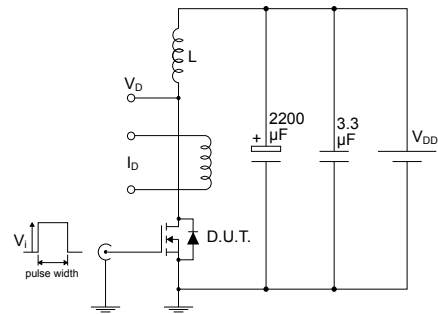
AM01468v1

**Figure 18. Test circuit for gate charge behavior**


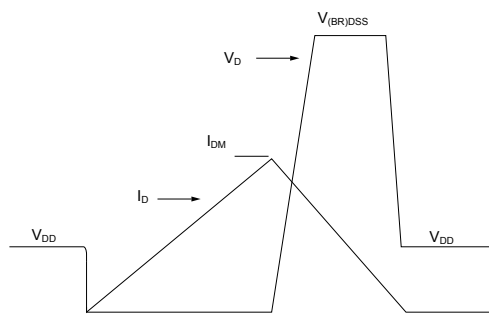
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**Figure 19. Test circuit for inductive load switching and diode recovery times**


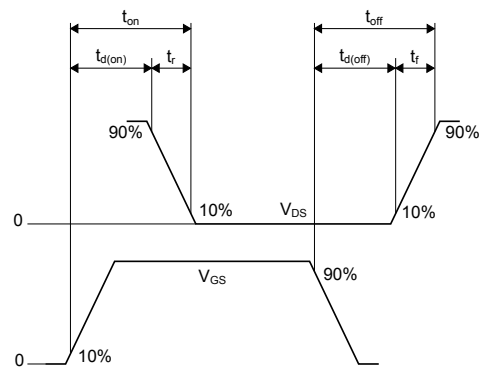
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**Figure 20. Unclamped inductive load test circuit**


AM01471v1

**Figure 21. Unclamped inductive waveform**


AM01472v1

**Figure 22. Switching time waveform**


AM01473v1



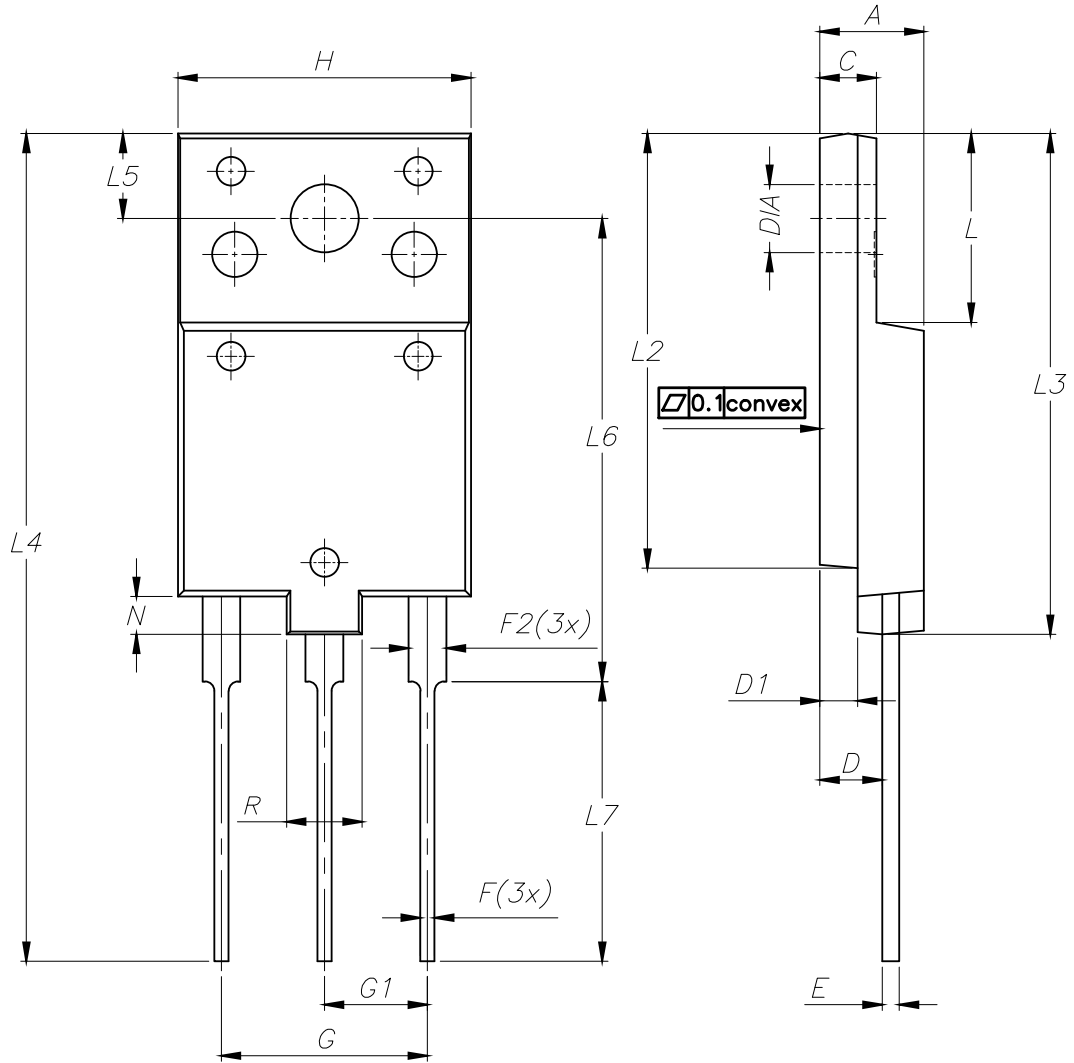
## 4 Package information

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In order to meet environmental requirements, ST offers these devices in different grades of **ECOPACK** packages, depending on their level of environmental compliance. ECOPACK specifications, grade definitions and product status are available at: [www.st.com](http://www.st.com). ECOPACK is an ST trademark.

### 4.1 TO-3PF type A package information

Figure 23. TO-3PF type A package outline



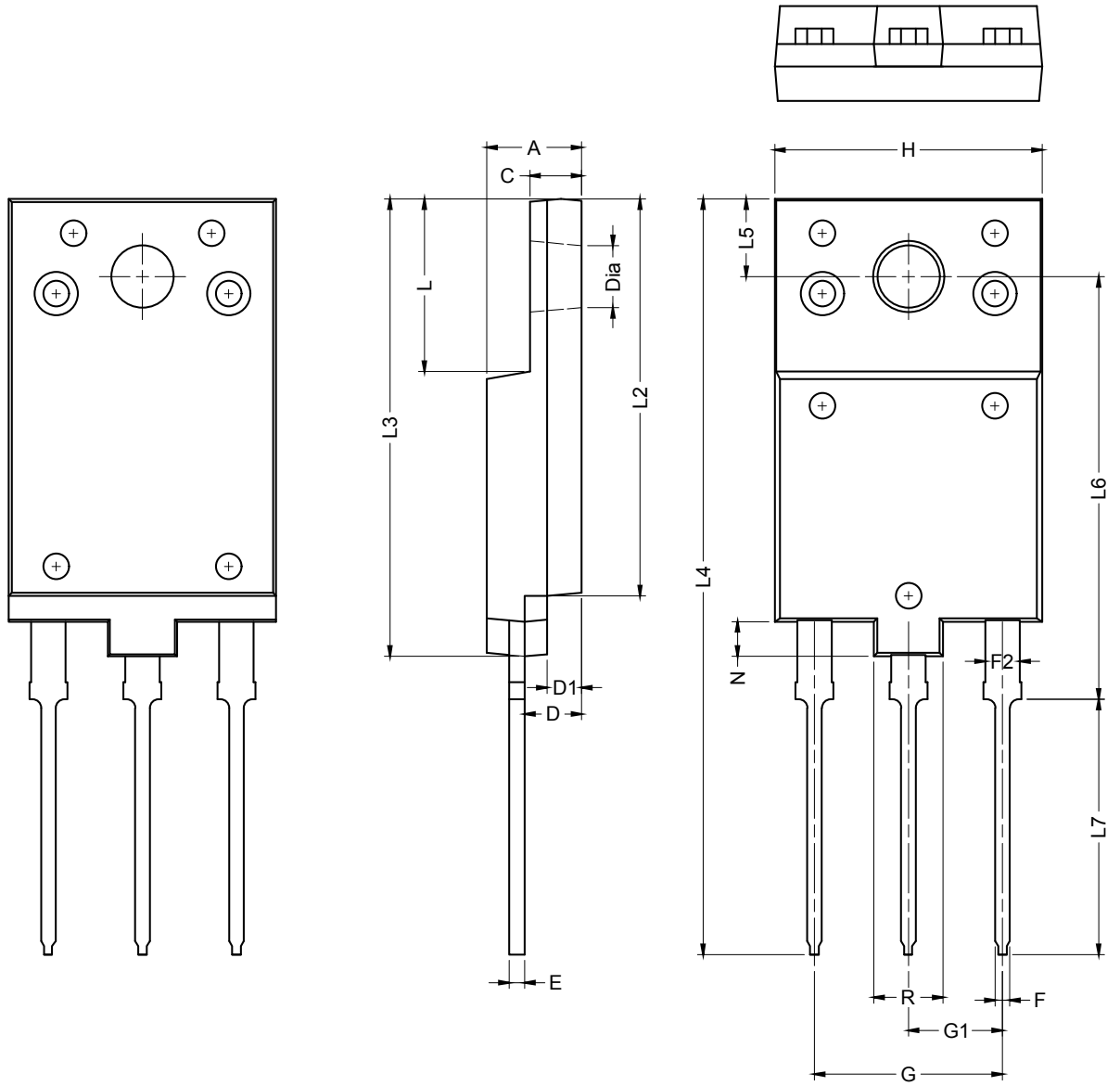
7627132\_type\_A\_8

**Table 8. TO-3PF type A mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	5.30		5.70
C	2.80		3.20
D	3.10		3.50
D1	1.80		2.20
E	0.80		1.00
F	0.65		0.85
F2	1.80		2.20
G	10.80		11.00
G1	5.35	5.45	5.55
H	15.30		15.70
L	9.80	10.00	10.20
L2	22.80		23.20
L3	26.30		26.70
L4	43.60		44.00
L5	4.30		4.70
L6	24.30		24.70
L7	14.60		15.00
N	1.80		2.20
R	3.80		4.20
Dia	3.40		3.80

## 4.2 TO-3PF type B package information

Figure 24. TO-3PF type B package outline



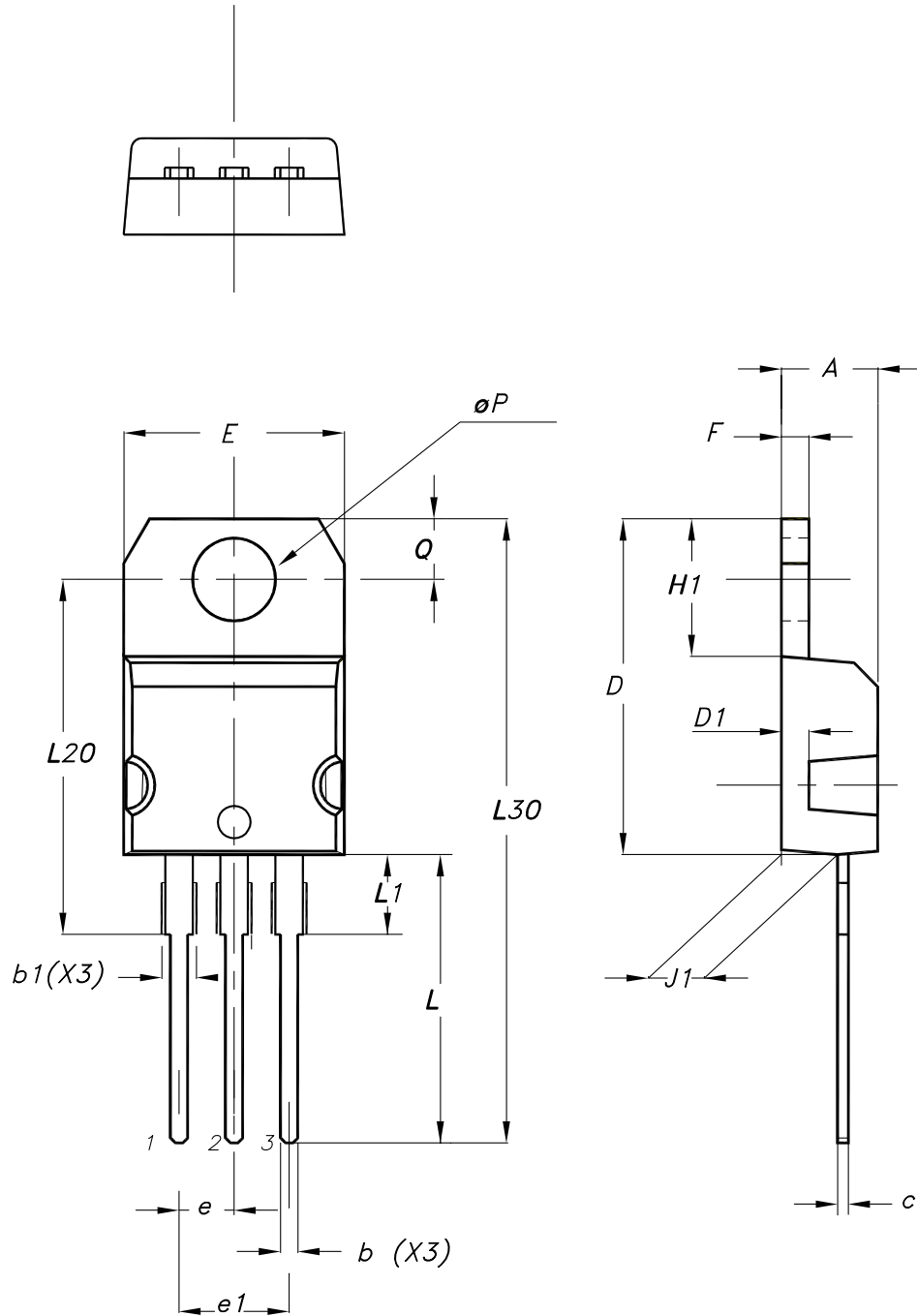
7627132\_type\_B\_8

**Table 9. TO-3PF type B mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	5.30	5.50	5.70
C	2.80	3.00	3.20
D	3.10	3.30	3.50
D1	1.80	2.00	2.20
E	0.80	0.95	1.10
F	0.65	0.80	0.95
F2	1.80	2.00	2.20
G	10.30	10.90	11.50
G1	5.25	5.45	5.65
H	15.30	15.50	15.70
L	9.80	10.00	10.20
L2	22.80	23.00	23.20
L3	26.30	26.50	26.70
L4	43.20	43.80	44.40
L5	4.30	4.50	4.70
L6	24.30	24.50	24.70
L7	14.60	14.80	15.00
N	1.80	2.00	2.20
R	3.80	4.00	4.20
Dia	3.40	3.60	3.80

### 4.3 TO-220 type A package information

Figure 25. TO-220 type A package outline



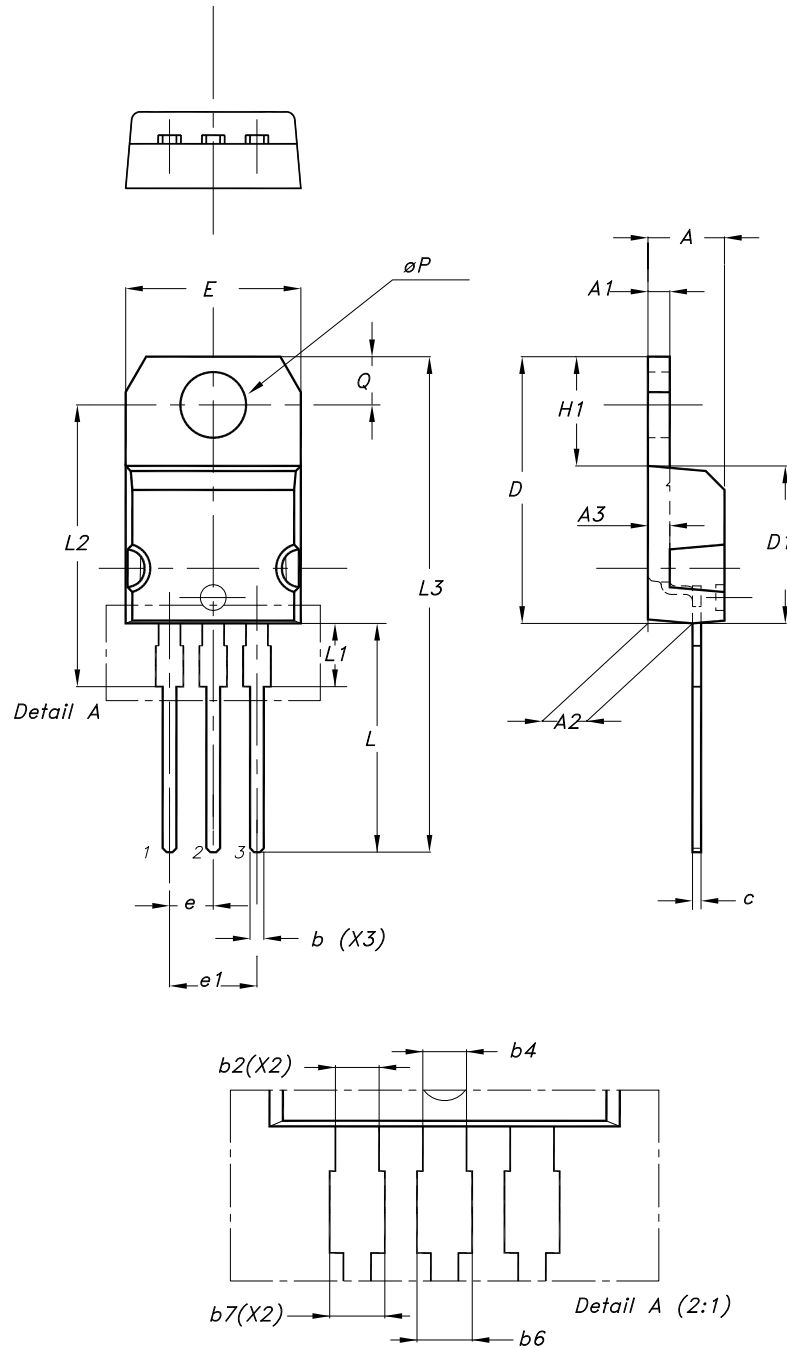
0015988\_typeA\_Rev\_23

**Table 10. TO-220 type A package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.40		4.60
b	0.61		0.88
b1	1.14		1.55
c	0.48		0.70
D	15.25		15.75
D1		1.27	
E	10.00		10.40
e	2.40		2.70
e1	4.95		5.15
F	1.23		1.32
H1	6.20		6.60
J1	2.40		2.72
L	13.00		14.00
L1	3.50		3.93
L20		16.40	
L30		28.90	
øP	3.75		3.85
Q	2.65		2.95
Slug flatness		0.03	0.10

#### 4.4 TO-220 type H package information

Figure 26. TO-220 type H package outline



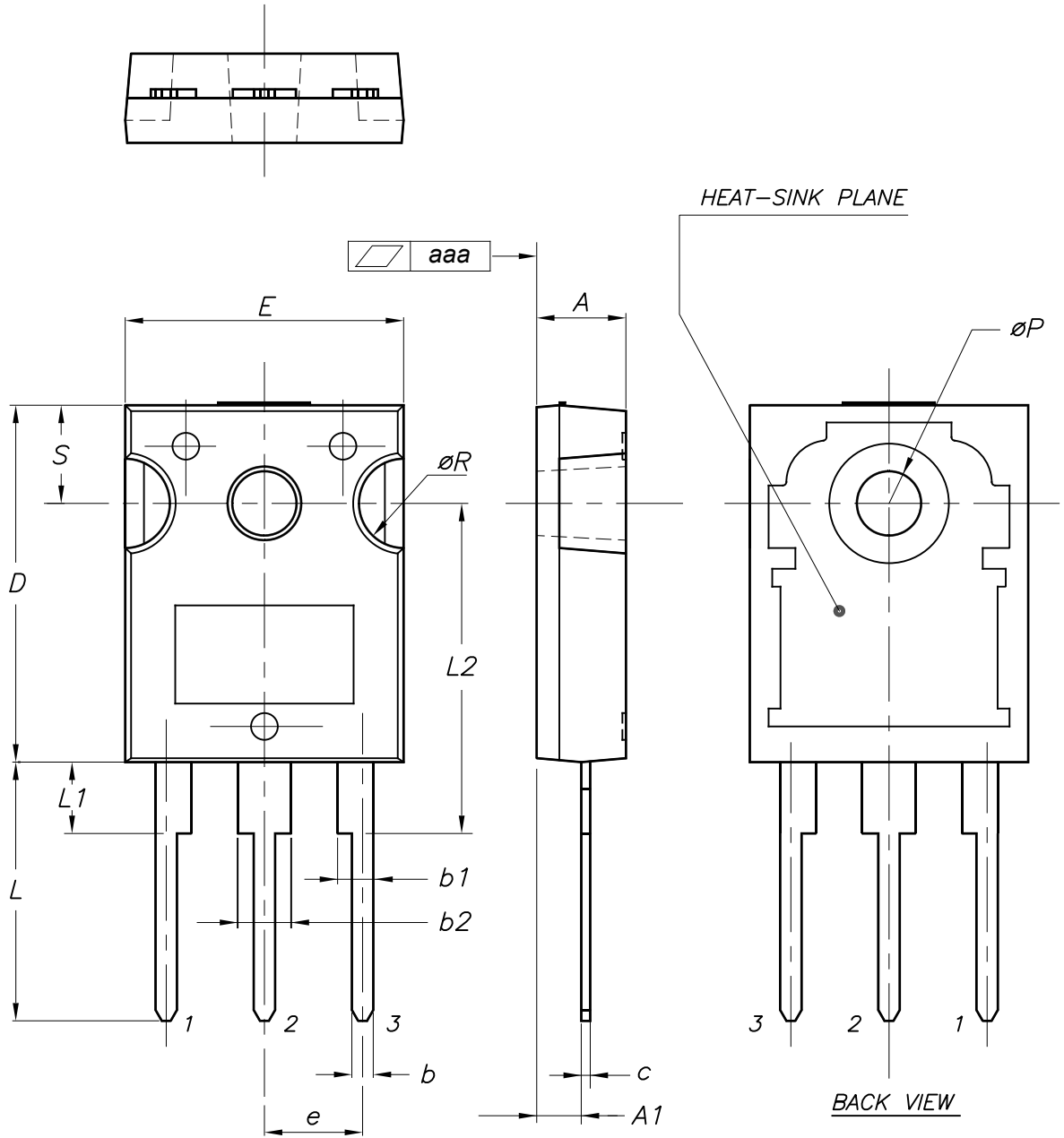
0015988\_H\_23

Table 11. TO-220 type H package mechanical data

Dim.	mm		
	Min.	Typ.	Max.
A	4.40	4.45	4.50
A1	1.22		1.32
A2	2.49	2.59	2.69
A3	1.17	1.27	1.37
b	0.78		0.87
b2	1.25		1.34
b4	1.20		1.29
b6			1.50
b7			1.45
c	0.49		0.56
D	15.40	15.50	15.60
D1	9.05	9.15	9.25
E	10.08	10.18	10.28
e	2.44	2.54	2.64
e1	4.98	5.08	5.18
H1	6.25	6.35	6.45
L	13.20	13.40	13.60
L1	3.50	3.70	3.90
L2	16.30	16.40	16.50
L3	28.70	28.90	29.10
ØP	3.75	3.80	3.85
Q	2.70	2.80	2.90
Slug flatness		0.03	0.10

4.5 TO-247 package information

Figure 27. TO-247 package outline



0075325\_10

**Table 12. TO-247 package mechanical data**

Dim.	mm		
	Min.	Typ.	Max.
A	4.85		5.15
A1	2.20		2.60
b	1.0		1.40
b1	2.0		2.40
b2	3.0		3.40
c	0.40		0.80
D	19.85		20.15
E	15.45		15.75
e	5.30	5.45	5.60
L	14.20		14.80
L1	3.70		4.30
L2		18.50	
ØP	3.55		3.65
ØR	4.50		5.50
S	5.30	5.50	5.70
aaa		0.04	0.10



## 5 Ordering information

Table 13. Order codes

Order codes	Marking	Package	Packing
STFW4N150	4N150	TO-3PF	Tube
STP4N150	P4N150	TO-220	
STW4N150	W4N150	TO-247	

## Revision history

**Table 14. Document revision history**

Date	Revision	Changes
29-Mar-2005	1	Initial release
07-Jul-2005	2	Removed TO-220FP
07-Oct-2005	3	Document status promoted from preliminary data to datasheet
10-Aug-2006	4	Document reformatted, no content change
06-Nov-2007	5	Updated unit on <i>Table 5: On/off states</i>
09-Apr-2008	6	Added new packages: TO-220FH, TO-3PF
21-Jan-2009	7	Remove package TO-220FH
23-Feb-2009	8	Added $P_{TOT}$ value for TO-3PF $P_{TOT}$ ( <i>Table 2: Absolute maximum ratings</i> )
23-Jul-2009	9	Added new figures: Figure 4: Safe operating area for TO-3PF and Figure 5: Thermal impedance for TO-3PF
08-Nov-2023	10	<p>Modified <a href="#">Features and Description</a> on cover page.</p> <p>Modified <a href="#">Table 4. Static</a>, <a href="#">Table 5. Dynamic</a> and <a href="#">Table 7. Source-drain diode</a>.</p> <p>Modified <a href="#">Figure 11. Typical gate charge characteristics</a>, <a href="#">Figure 12. Typical capacitance characteristics</a> and <a href="#">Figure 16. Maximum avalanche energy vs temperature</a>.</p> <p>Updated <a href="#">Section 4 Package information</a>.</p> <p>Minor text changes.</p>



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